

December 2010

FDB8860

N-Channel Logic Level PowerTrench® MOSFET 30V, 80A, 2.6m Ω

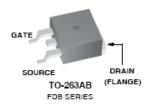
Features

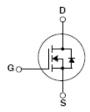
Applications

- $R_{DS(ON)} = 1.9 \text{m}\Omega$ (Typ), $V_{GS} = 5\text{V}$, $I_D = 80\text{A}$
- DC-DC Converters

- $Q_{g(5)} = 89nC \text{ (Typ)}, V_{GS} = 5V$
- Low Miller Charge
- Low Q_{RR} Body Diode
- UIS Capability (Single Pulse and Repetitive Pulse)
- RoHS Compliant







MOSFET Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	±20	V
	Drain Current Continuous (V _{GS} = 10V, T _C < 163°C)	80	Α
I _D	Continuous (V _{GS} = 5V, T _C < 162°C)	80	Α
	Continuous ($V_{GS} = 10V$, $T_C = 25^{\circ}C$, with $R_{\theta JA} = 43^{\circ}C/W$)	31	Α
	Pulsed	Figure 4	Α
E _{AS}	Single Pulse Avalanche Energy (Note 1)	947	mJ
В	Power Dissipation	254	W
P_{D}	Derate above 25°C	1.7	W/°C
T_J , T_{STG}	Operating and Storage Temperature	-55 to +175	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case	0.59	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient (Note 2)	62	°C/W
$R_{\theta JA}$	R _{0JA} Thermal Resistance Junction to Ambient TO-263,1in ² copper pad area 43		°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB8860	FDB8860	TO-263AB	330mm	24mm	800units

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

Parameter

Off Cha	Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 1mA, V_{GS}$	= 0V	30	-	-	V
	Zero Gate Voltage Drain Current	V _{DS} = 24V		-	-	1	μА
DSS	Zero Gate Voltage Drain Current	$V_{GS} = 0V$	$T_J = 150$ °C	-	-	250	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$		-	-	±100	nA

Test Conditions

Min

Тур

Max

Units

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	1.7	3	V
		$I_D = 80A, V_{GS} = 10V$	-	1.6	2.3	
		$I_D = 80A, V_{GS} = 5V$	-	1.9	2.6	
R _{DS(ON)}	R _{DS(ON)} Drain to Source On Resistance	$I_D = 80A, V_{GS} = 4.5V$	-	2.1	2.7	mΩ
	I _D = 80A, V _{GS} = 10V, T _J = 175°C	-	2.5	3.6		

Dynamic Characteristics

C _{ISS}	Input Capacitance	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz		-	9460	12585	pF
C _{OSS}	Output Capacitance			-	1710	2275	pF
C _{RSS}	Reverse Transfer Capacitance	1 - 1101112		-	1050	1575	pF
R_{G}	Gate Resistance	f = 1MHz		-	1.8	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at 10V	V _{GS} = 0V to 10V		-	165	214	nC
$Q_{g(5)}$	Total Gate Charge at 5V	$V_{GS} = 0V \text{ to } 5V$		-	89	115	nC
$Q_{g(TH)}$	Threshold Gate Charge	$V_{GS} = 0V \text{ to } 1V$	$V_{DD} = 15V$ $I_D = 80A$	-	9.1	12	nC
Q_{gs}	Gate to Source Gate Charge		$I_0 = 60A$ $I_0 = 1.0mA$	-	26	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau		.g	-	18	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	33	-	nC

Electrical Characteristics $T_J = 25^{\circ}\text{C}$ unless otherwise noted

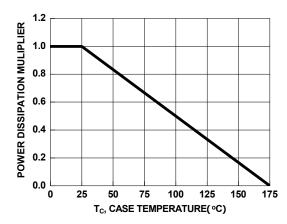
Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Switching	g Characteristics					
t _(on)	Turn-On Time		-	-	340	ns
t _{d(on)}	Turn-On Delay Time		-	14	-	ns
t _r	Turn-On Rise Time	V _{DD} = 15V, I _D = 80A	-	213	-	ns
t _{d(off)}	Turn-Off Delay Time	$V_{DD} = 15V, I_{D} = 80A$ $V_{GS} = 5V, R_{GS} = 1\Omega$	-	79	-	ns
t _f	Turn-Off Fall Time		-	49	-	ns
t _{off}	Turn-Off Time		-	-	192	ns

Drain-Source Diode Characteristics

V _{SD} Source to Drain Diode Voltage	Source to Drain Diode Voltage	I _{SD} = 80A	-	-	1.25	V
	I _{SD} = 40A	-	-	1.0	V	
t _{rr}	Reverse Recovery Time	$I_{SD} = 80A$, $dI_{SD}/dt = 100A/\mu s$	-	-	43	ns
Q _{rr}	Reverse Recovery Charge	$I_{SD} = 80A$, $dI_{SD}/dt = 100A/\mu s$	-	-	29	nC

Notes: 1: Starting T_J = 25°C, L =0.47mH, I_{AS} = 64A , V_{DD} = 30V, V_{GS} = 10V. 2: Pulse width = 100s

Typical Characteristics $T_J = 25$ °C unless otherwise noted



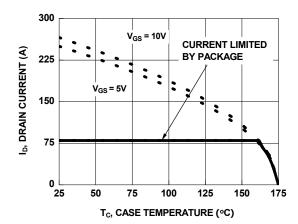


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature

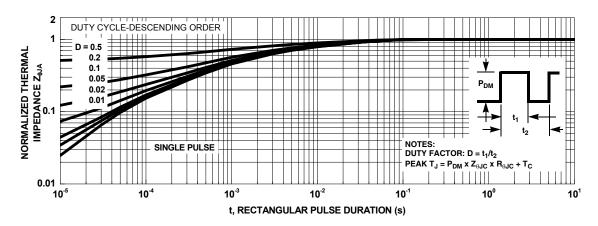


Figure 3. Normalized Maximum Transient Thermal Impedance

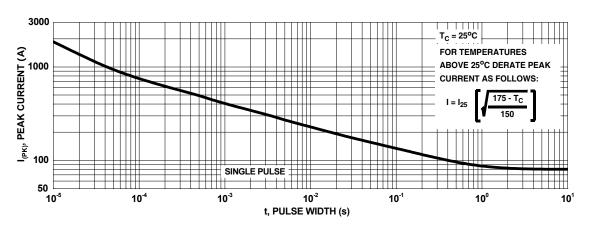
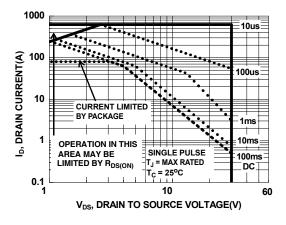


Figure 4. Peak Current Capability

Typical Characteristics T_J = 25°C unless otherwise noted



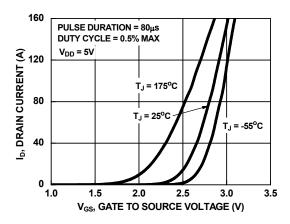
 $\begin{array}{c} 500 \\ \hline \text{If R = 0} \\ \hline \text{T}_{AV} = (\text{L})(\text{I}_{AS})'(1.3\text{*RATED BV}_{DSS} - \text{V}_{DD}) \\ \hline \text{If R $\neq 0$} \\ \hline \text{T}_{AV} = (\text{L}/\text{R})\ln[(\text{I}_{AS}\text{*R})/(1.3\text{*RATED BV}_{DSS} - \text{V}_{DD}) + 1] \\ \hline \\ \text{STARTING T}_{J} = 25^{\circ}\text{C} \\ \hline \\ \text{STARTING T}_{J} = 150^{\circ}\text{C} \\ \hline \\ \text{STARTING T}_{$

Figure 5. Forward Bias Safe Operating Area

NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability



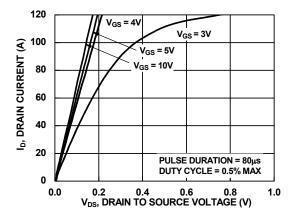
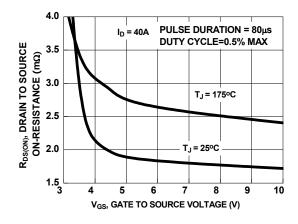


Figure 7. Transfer Characteristics

Figure 8. Saturation Characteristics



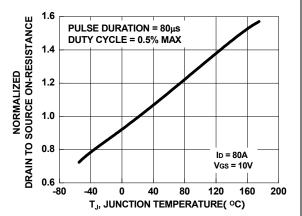


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted

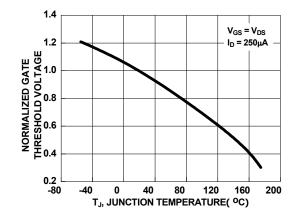


Figure 11. Normalized Gate Threshold Voltage vs
Junction Temperature

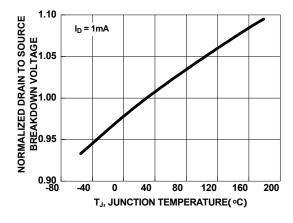


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

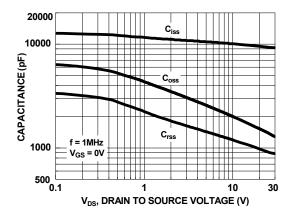


Figure 13. Capacitance vs Drain to Source Voltage

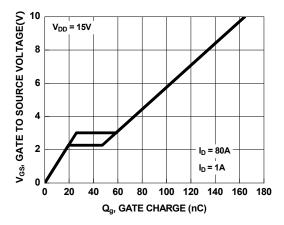


Figure 14. Gate Charge vs Gate to Source Voltage





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